



P-Channel Enhancement Mode MOSFET

Feature

-30V/-3.2A, RDS(ON) =55m Ω (MAX) @VGS = -10V.

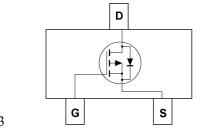
 $RDS(ON) = 70m\Omega(MAX)$ @VGS = -4.5V.

 $RDS(ON) = 120m\Omega(MAX)$ @VGS = -2.5V.

Super High dense cell design for extremely low $R^{\mathrm{DS}(\mathrm{ON})}$

Reliable and Rugged

SOT-23 for Surface Mount Package





Applications

Power Management

Portable Equipment and Battery Powered Systems.

Absolute Maximum Ratings TA=25 °C Unless Otherwise noted

Parameter	neter Symbol Limit		Units	
Drain-Source Voltage	$V_{ m DS}$	-30	V	
Gate-Source Voltage	V_{GS}	±12	V	
Drain Current-Continuous	I_D	-3.2	A	

Electrical Characteristics TA=25°C Unless Otherwise noted

Parameter	Symbol	Test Conditions	Min	Тур.	Max	Units
Off Characteristics						
Drain to Source Breakdown Voltage	BVDSS	VGS=0V, ID=-250μA	-30	-	-	V
Zero-Gate Voltage Drain Current	IDSS	VDS=-24V, VGS=0V	-	-	-1	μΑ
Gate Body Leakage Current, Forward	IGSSF	VGS=12V, VDS=0V	-	-	100	nA
Gate Body Leakage Current, Reverse	IGSSR	VGS=-12V, VDS=0V	-	-	-100	nA
On Characteristics			•		•	
Gate Threshold Voltage	VGS(th)	VGS= VDS, ID=-250µA	-0.7	-	-1.3	V
Static Drain-source On-Resistance	RDS(ON)	VGS =-10V, ID =-3.2A	-	50	55	mΩ
		VGS = -4.5V, ID = -3.0A	-	60	70	mΩ
		VGS =-2.5V, ID =-1.0A	-	80	120	mΩ
Drain-Source Diode Characteristics	s and Maximum Ra	tings			•	
Drain-Source Diode Forward Voltage	VSD	VGS =0V, IS=-1.0A			-1.0	V

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Typical Characteristics

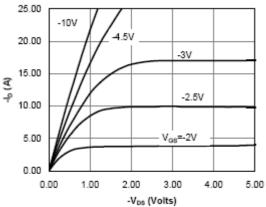


Fig 1: On-Region Characteristics

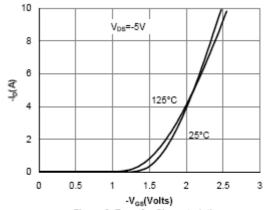


Figure 2: Transfer Characteristics

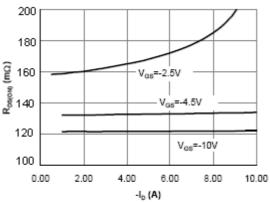
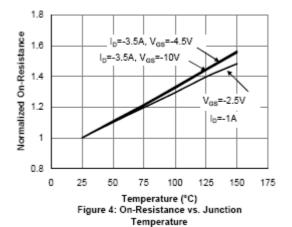


Figure 3: On-Resistance vs. Drain Current and Gate Voltage



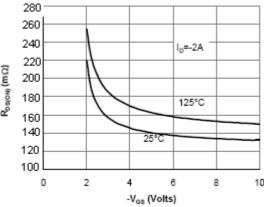


Figure 5: On-Resistance vs. Gate-Source Voltage

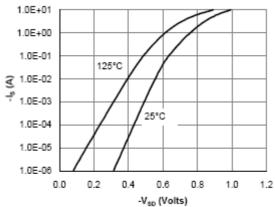


Figure 6: Body-Diode Characteristics





Package Outline Dimensions (UNIT: mm)

SOT-23

